TEXAS INSTRUMENTS
Data sheet acquired from Harris Semiconductor
SCHS045C – Revised October 2003

CD4048B Types

CMOS Multifunction Expandable 8-Input Gate

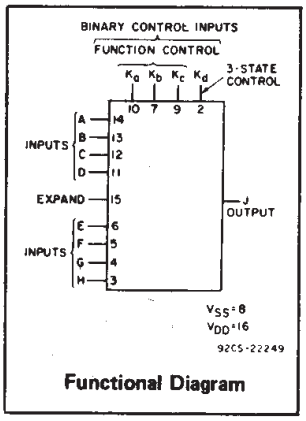
High-Voltage Types (20-Volt Rating)

■ CD4048B is an 8-input gate having four control inputs. Three binary control inputs — Ka, Kb, and Kc — provide the implementation of eight different logic functions. These functions are OR, NOR, AND, NAND, OR/AND, OR/NAND, AND/OR and AND/NOR.

A fourth control input, Kd, provides the user with a 3-state output. When control input Kd is high, the output is either a logic 1 or a logic 0 depending on the inner states. When control input Kd is low, the output is an open circuit. This feature enables the user to connect this device to a common bus line.

In addition to the eight input lines, an EXPAND input is provided that permits the user to increase the number of inputs into a CD4048B (see Fig. 2). For example, two CD4048Bs can be cascaded to provide a 16-input multifunction gate. When the EXPAND input is not used, it should be connected to V_{SS}.

The CD4048B-series types are supplied in 16-lead hermetic dual-in-line ceramic packages (F3A suffix), 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline packages (M, M96, MT, and NSR suffixes), and 16-lead thin shrink small-outline packages (PW and PWR suffixes).



Functional Diagram

MAXIMUM RATINGS, *Absolute-Maximum Values:*

DC SUPPLY-VOLTAGE RANGE, (V_{DD})
(Voltages referenced to V_{SS} Terminal) ..... -0.5V to +20V
INPUT VOLTAGE RANGE, ALL INPUTS ..... -0.5V to V_{DD} +0.5V
DC INPUT CURRENT, ANY ONE INPUT ..... ±10mA
POWER DISSIPATION PER PACKAGE (P_D):
For T_A = -55°C to +100°C 500mW
For T_A = +100°C to +125°C ..... Derate Linearity at 12mW/°C to 200mW
DEVICE DISSIPATION PER OUTPUT TRANSISTOR
FOR T_A = FULL PACKAGE-TEMPERATURE RANGE (All Package Types) 100mW
OPERATING-TEMPERATURE RANGE (T_A) ..... -55°C to +125°C
STORAGE TEMPERATURE RANGE (T_{stg}) ..... -65°C to +150°C
LEAD TEMPERATURE (DURING SOLDERING):
At distance 1/16 ± 1/32 inch (1.59 ± 0.79mm) from case for 10s max ..... +265°C

Features:

- Three-state output
- Many logic functions available in one package
- Standardized, symmetrical output characteristics
- 100% tested for quiescent current at 20 V
- Maximum input current of 1 μA at 18 V (full package-temperature range), 100 nA at 18 V and 25°C
- Noise margin (full package-temperature range) = 1 V at V_{DD}=5 V, 2 V at V_{DD} = 10 V, 2.5 V at V_{DD}=15 V
- 5-V, 10-V, and 15-V parametric ratings
- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"

Applications:

- Selection of up to 8 logic functions
- Digital control of logic
- General-purpose gating logic
  - Decoding
  - Encoding

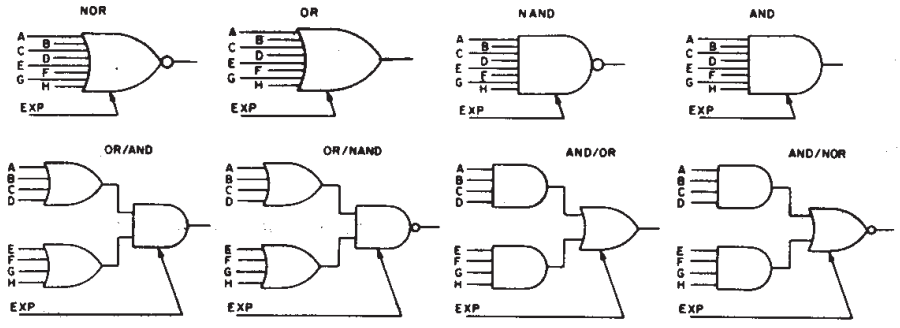
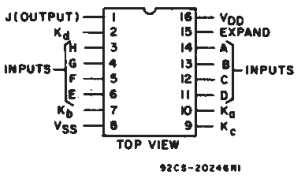


Fig. 1 — Basic logic configurations.



TERMINAL ASSIGNMENT

RECOMMENDED OPERATING CONDITIONS

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	LIMITS		UNITS
	MIN.	MAX.	
Supply-Voltage Range (For T_A = Full Package Temperature Range)	3	18	V

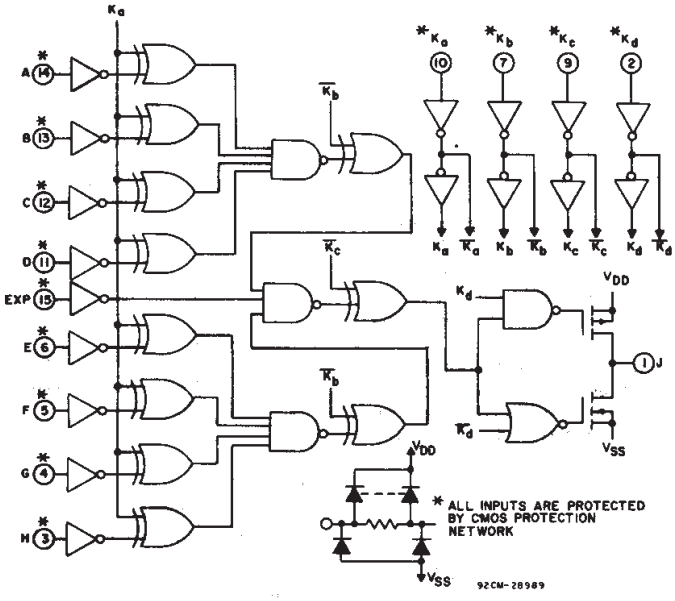


Fig. 2 – Logic diagram.

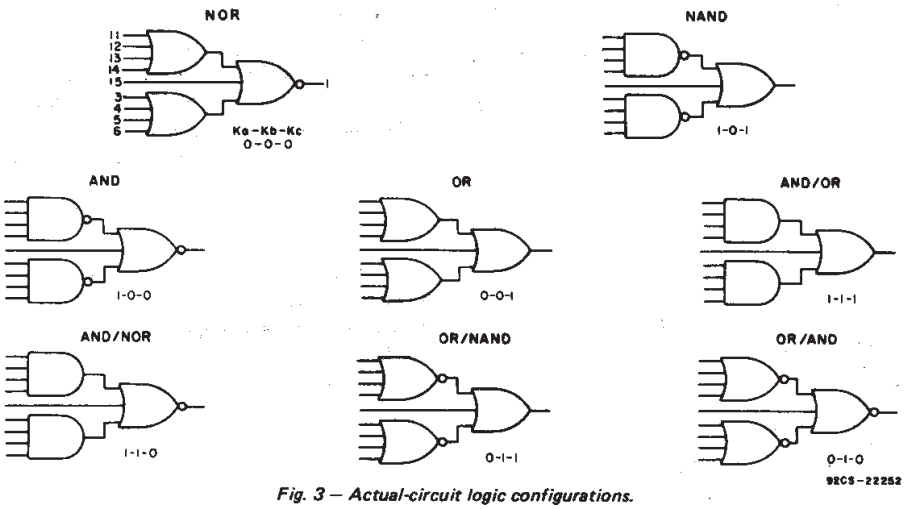


Fig. 3 – Actual-circuit logic configurations.

APPLICATIONS OF EXPAND INPUT

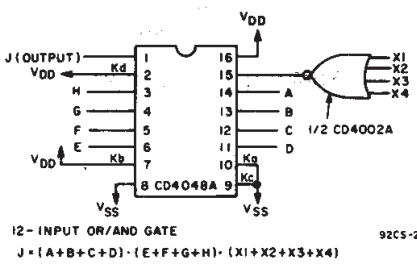


Fig. 4 – 12-input OR/AND gate.

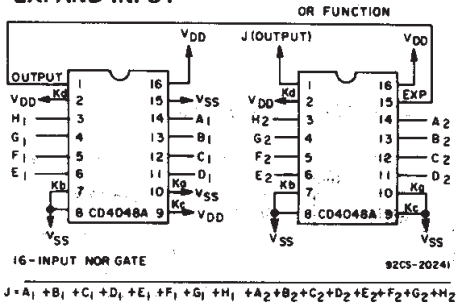


Fig. 5 – 16-input NOR gate.

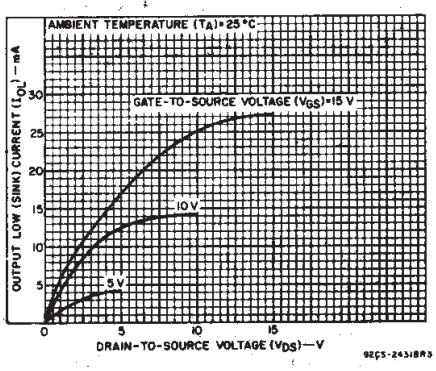


Fig. 6 – Typical output low (sink) current characteristics.

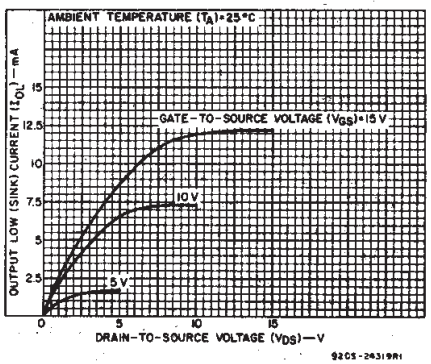


Fig. 7 – Minimum output low (sink) current characteristics.

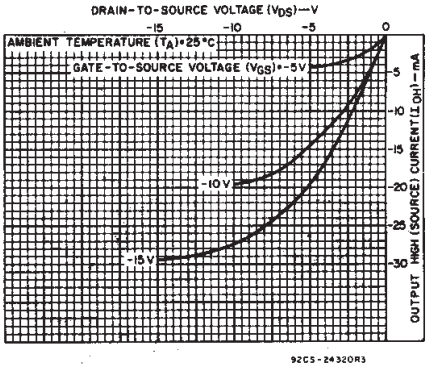


Fig. 8 – Typical output high (source) current characteristics.

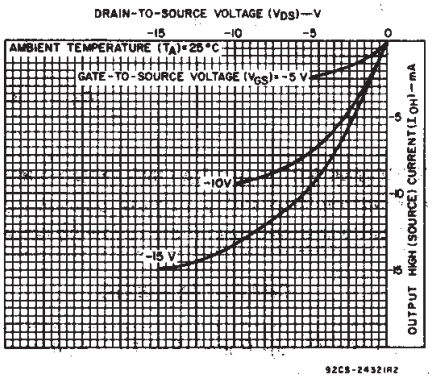


Fig. 9 – Minimum output high (source) current characteristics.

STATIC ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
								+25			
	V_O (V)	V_{IN} (V)	V_{DD} (V)	−55	−40	+85	+125	Min.	Typ.	Max.	
Quiescent Device Current, I_{DD} Max.	–	0,5	5	0.25	0.25	7.5	7.5	–	0.01	0.25	μA
	–	0,10	10	0.5	0.5	15	15	–	0.01	0.5	
	–	0,15	15	1	1	30	30	–	0.01	1	
	–	0,20	20	5	5	150	150	–	0.02	5	
Output Low (Sink) Current I_{OL} Min.	0.4	0,5	5	0.64	0.61	0.42	0.36	0.51	1	–	mA
	0.5	0,10	10	1.6	1.5	1.1	0.9	1.3	2.6	–	
	1.5	0,15	15	4.2	4	2.8	2.4	3.4	6.8	–	
Output High (Source) Current, I_{OH} Min.	4.6	0,5	5	−0.64	−0.61	−0.42	−0.36	−0.51	−1	–	
	2.5	0,5	5	−2	−1.8	−1.3	−1.15	−1.6	−3.2	–	
	9.5	0,10	10	−1.6	−1.5	−1.1	−0.9	−1.3	−2.6	–	
	13.5	0,15	15	−4.2	−4	−2.8	−2.4	−3.4	−6.8	–	
Output Voltage: Low-Level, V_{OL} Max.	–	0,5	5	0.05				–	0	0.05	V
	–	0,10	10	0.05				–	0	0.05	
	–	0,15	15	0.05				–	0	0.05	
Output Voltage: High-Level, V_{OH} Min.	–	0,5	5	4.95				4.95	5	–	
	–	0,10	10	9.95				9.95	10	–	
	–	0,15	15	14.95				14.95	15	–	
Input Low Voltage, V_{IL} Max.	0.5,4.5	–	5	1.5				—	—	1.5	V
	1,9	–	10	3				—	—	3	
	1.5,13.5	–	15	4				—	—	4	
Input High Voltage, V_{IH} Min.	0.5,4.5	–	5	3.5				3.5	—	—	
	1,9	–	10	7				7	—	—	
	1.5,13.5	–	15	11				11	—	—	
Input Current I_{IN} Max.		0,18	18	±0.1	±0.1	±1	±1	–	$\pm 10^{-5}$	±0.1	μA
3-State Output Current, I_{OUT}	0,18	0,18	18	±0.4	±0.4	±12	±12	–	$\pm 10^{-4}$	±0.4	μA

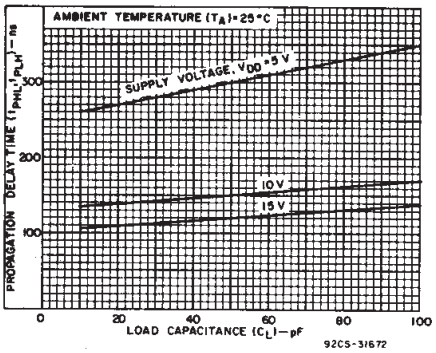


Fig. 10 – Typical propagation delay time (logic inputs to output) as a function of load capacitance.

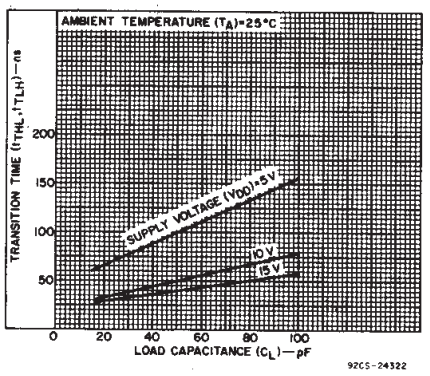


Fig. 11 – Typical transition time vs. load capacitance.

IMPLEMENTATION OF EXPAND INPUT FOR 9 OR MORE INPUTS

OUTPUT FUNCTION	FUNCTION NEEDED AT EXPAND INPUT	OUTPUT BOOLEAN EXPRESSION
NOR	OR	$J=\overline{(A+B+C+D+E+F+G+H)+(EXP)}$
OR	OR	$J=(A+B+C+D+E+F+G+H)+(EXP)$
AND	NAND	$J=(ABCDEFGH)\cdot\overline{(EXP)}$
NAND	NAND	$J=\overline{(ABCDEFGH)\cdot\overline{(EXP)}}$
OR/AND	NOR	$J=\overline{(A+B+C+D)\cdot(E+F+G+H)\cdot\overline{(EXP)}}$
OR/NAND	NOR	$J=\overline{(A+B+C+D)\cdot(E+F+G+H)\cdot\overline{(EXP)}}$
AND/NOR	AND	$J=\overline{(ABCD)+(EFGH)+(EXP)}$
AND/OR	AND	$J=(ABCD)+(EFGH)+(EXP)$

Note: (EXP) designates the EXPAND function (i.e., $X_1+X_2+\ldots X_N$).

NOTE:
Refer to FUNCTION TRUTH TABLE for connection of unused inputs.

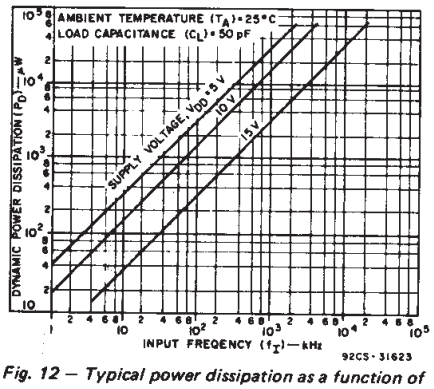


Fig. 12 – Typical power dissipation as a function of input frequency.

DYNAMIC CHARACTERISTICS at T_A=25°C, C_L=50 pF, Input t_r,t_f=20 ns, R_L=200 kΩ unless otherwise specified

CHARACTERISTIC	TEST CONDITIONS	V_{DD} V	LIMITS All Package Types Typ.	LIMITS All Package Types Max.	UNITS
Propagation Delay: t_{PHL},t_{PLH} Inputs to Output and Ka to Output		5	300	600	ns
		10	150	300	
		15	120	240	
Kb to Output		5	225	450	
		10	85	170	
		15	55	110	
Kc to Output		5	140	280	
		10	50	100	
		15	40	80	
Expand Input to Output		5	190	380	
		10	90	180	
		15	65	130	
3-State Propagation Delay: Kd to Output t_{PHZ},t_{PLZ} t_{PZH},t_{PZL}	R_L=1 kΩ See Fig.21	5	80	160	
		10	35	70	
		15	25	50	
Transition Time: t_{THL},t_{TLH}		5	100	200	
		10	50	100	
		15	40	80	
Input Capacitance: C_I	Any Input		5	7	pF
3-State Output Capacitance			5	10	

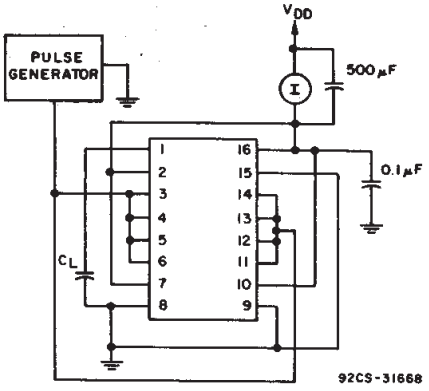


Fig. 13 – Dynamic power dissipation test circuit.

FUNCTION TRUTH TABLE

OUTPUT FUNCTION	BOOLEAN EXPRESSION	K_a	K_b	K_c	UNUSED INPUT*
NOR	$J=\overline{A+B+C+D+E+F+G+H}$	0	0	0	V_{SS}
OR	J=A+B+C+D+E+F+G+H	0	0	1	V_{SS}
OR/AND	J=(A+B+C+D)·(E+F+G+H)	0	1	0	V_{SS}
OR/NAND	$J=\overline{(A+B+C+D)\cdot(E+F+G+H)}$	0	1	1	V_{SS}
AND	J=ABCDEFGH	1	0	0	V_{DD}
NAND	$J=\overline{ABCDEFGH}$	1	0	1	V_{DD}
AND/NOR	$J=\overline{ABCD+EFGH}$	1	1	0	V_{DD}
AND/OR	J=ABCD+EFGH	1	1	1	V_{DD}

K_d=1 Normal Inverter Action

K_d=0 High Impedance Output

EXPAND Input=0

* See Figs. 1,2,3,4, and 5.

TEST CIRCUITS - STATIC MEASUREMENTS

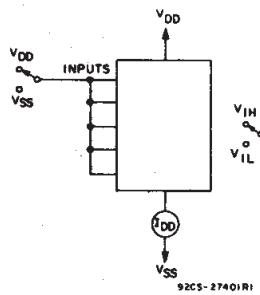


Fig. 14 – Quiescent device current test circuit.

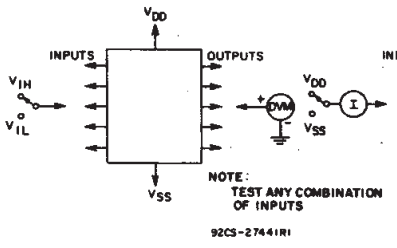


Fig. 15 – Input voltage test circuit.

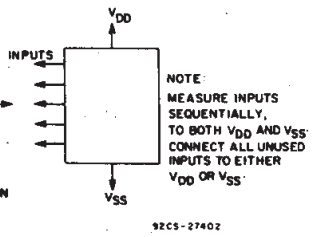


Fig. 16 – Input current test circuit.

TEST CIRCUITS - DYNAMIC MEASUREMENTS

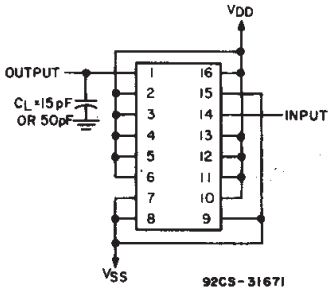


Fig. 17 – Test circuit for t_{PHL}, t_{THL}, and t_{TLH} (AND) measurements.

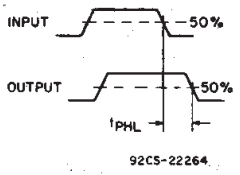


Fig. 18 – Waveforms for t_{PHL} and t_{PHL} (AND).

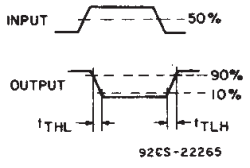


Fig. 19 – Waveforms for t_{THL} and t_{TLH} (AND).

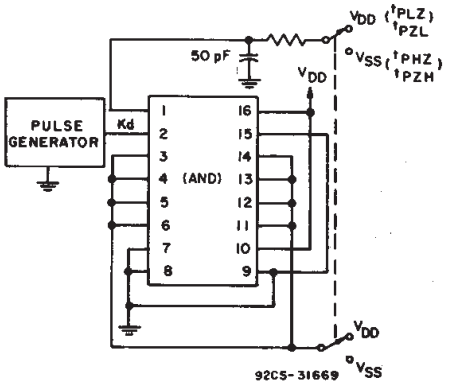


Fig. 20 – Test circuit for t_{PZL}, t_{PZH}, t_{PLZ}, and t_{PHZ} (AND).

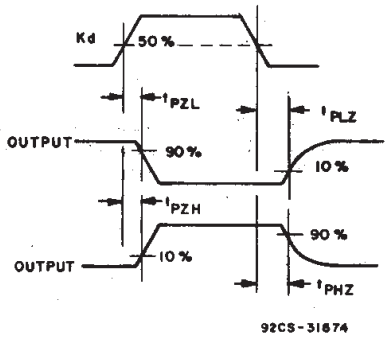
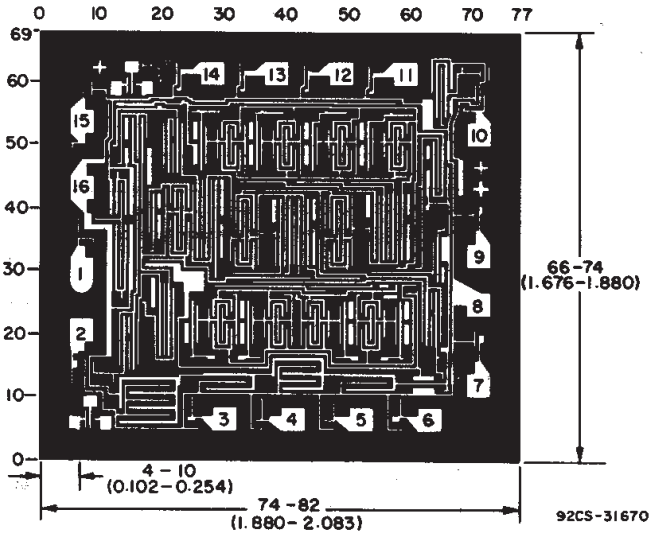


Fig. 21 – Waveforms for t_{PZL}, t_{PZH}, t_{PLZ}, and t_{PHZ} (AND).



Dimensions and pad layout for CD4048BH.

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch).

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
CD4048BE	Active	Production	PDIP (N) | 16	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD4048BE
CD4048BE.A	Active	Production	PDIP (N) | 16	25 | TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD4048BE
CD4048BF3A	Active	Production	CDIP (J) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	CD4048BF3A
CD4048BF3A.A	Active	Production	CDIP (J) | 16	25 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	CD4048BF3A
CD4048BM	Obsolete	Production	SOIC (D) | 16	-	-	Call TI	Call TI	-55 to 125	CD4048BM
CD4048BM96	Active	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4048BM
CD4048BM96.A	Active	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4048BM
CD4048BPW	Active	Production	TSSOP (PW) | 16	90 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM048B
CD4048BPW.A	Active	Production	TSSOP (PW) | 16	90 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM048B

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF CD4048B, CD4048B-MIL :

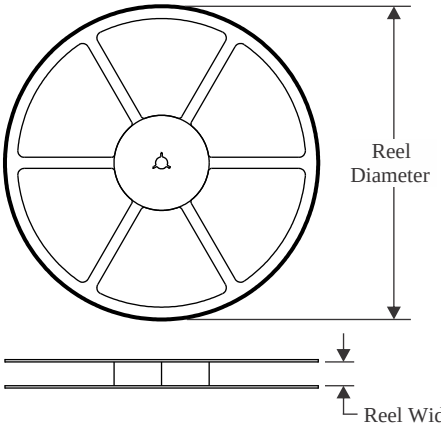
- Catalog : CD4048B
- Military : CD4048B-MIL

NOTE: Qualified Version Definitions:

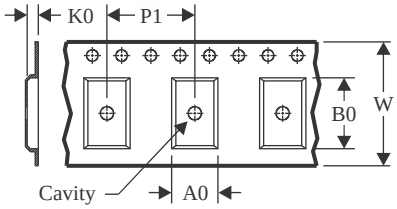
- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS

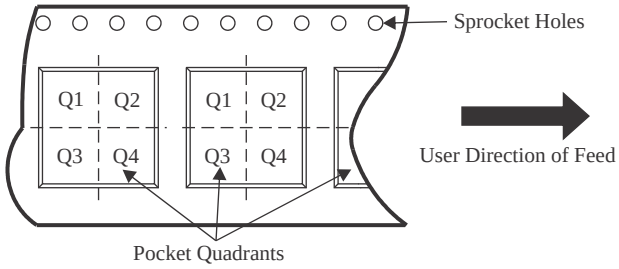


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

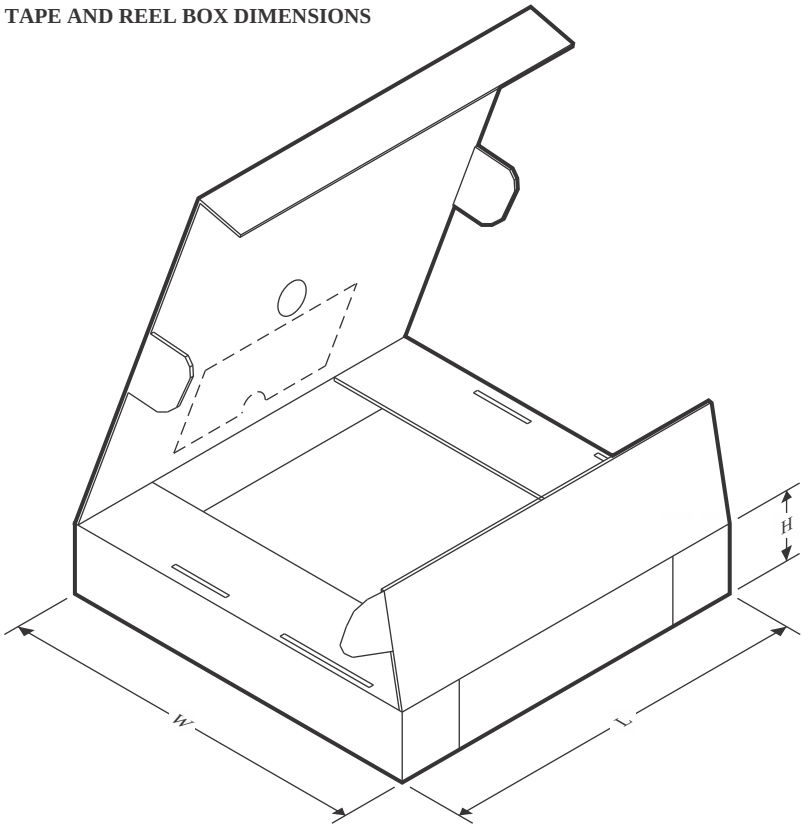
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD4048BM96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

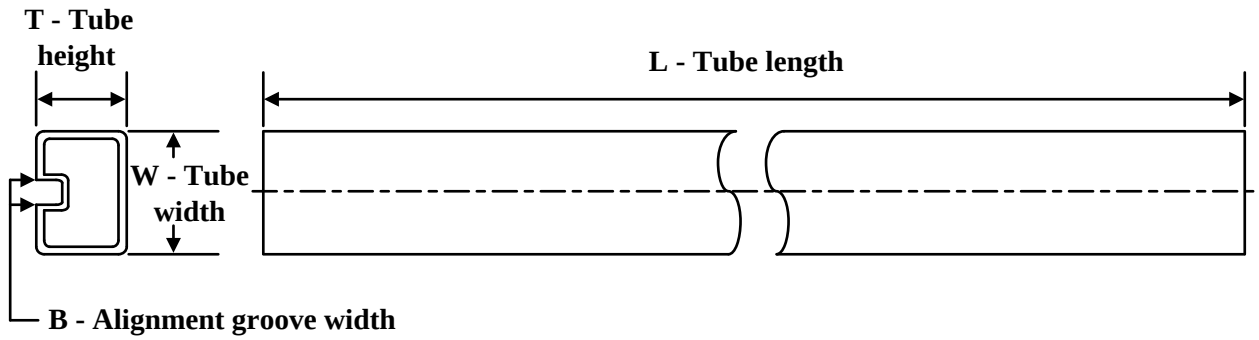
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD4048BM96	SOIC	D	16	2500	340.5	336.1	32.0

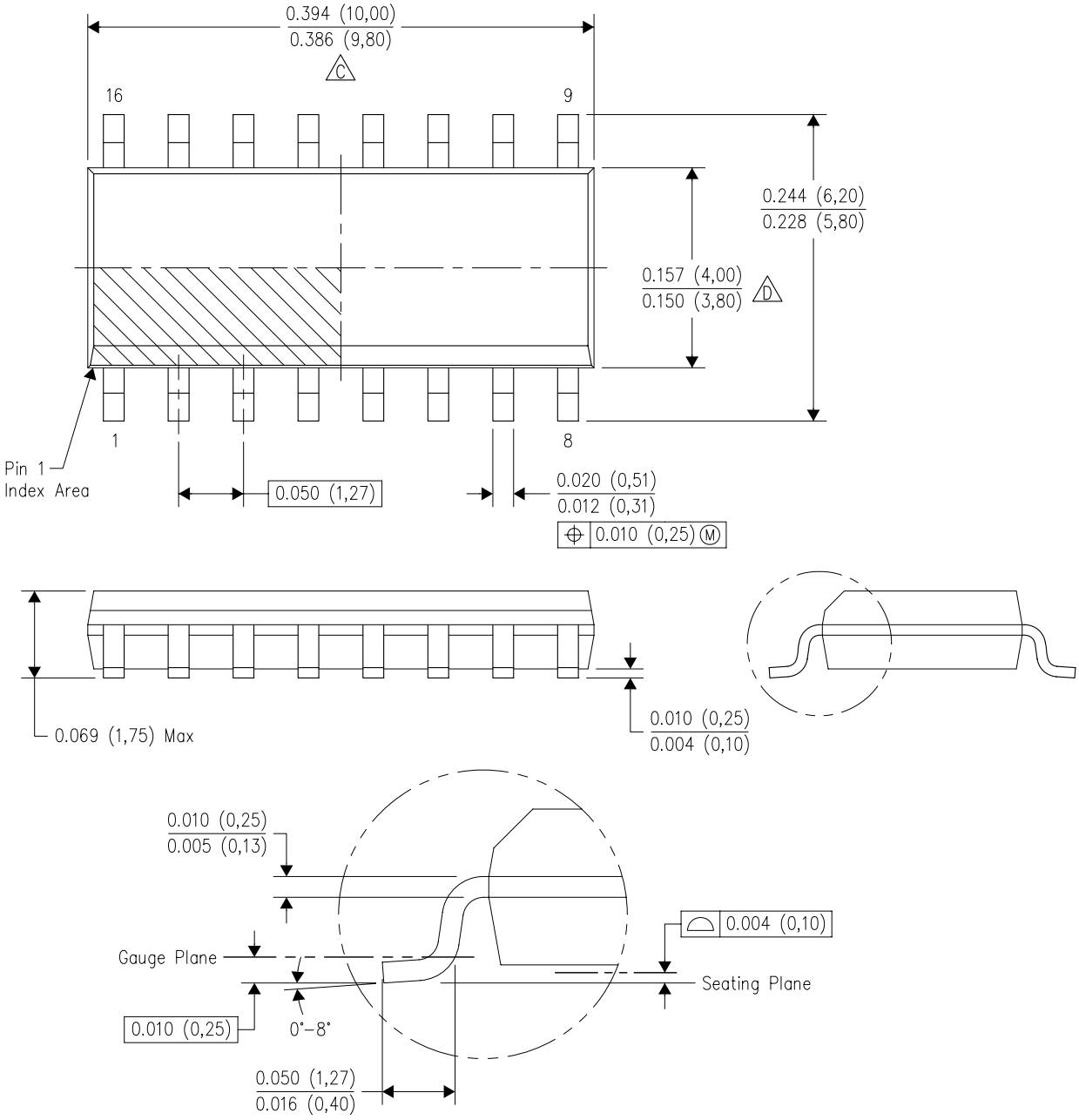
TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
CD4048BE	N	PDIP	16	25	506	13.97	11230	4.32
CD4048BE	N	PDIP	16	25	506	13.97	11230	4.32
CD4048BE.A	N	PDIP	16	25	506	13.97	11230	4.32
CD4048BE.A	N	PDIP	16	25	506	13.97	11230	4.32
CD4048BPW	PW	TSSOP	16	90	530	10.2	3600	3.5
CD4048BPW.A	PW	TSSOP	16	90	530	10.2	3600	3.5

D (R–PDSO–G16) PLASTIC SMALL OUTLINE

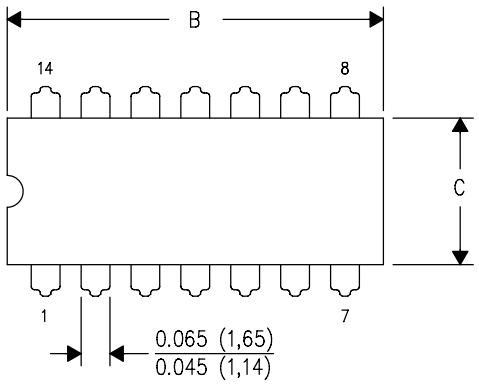


NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AC.

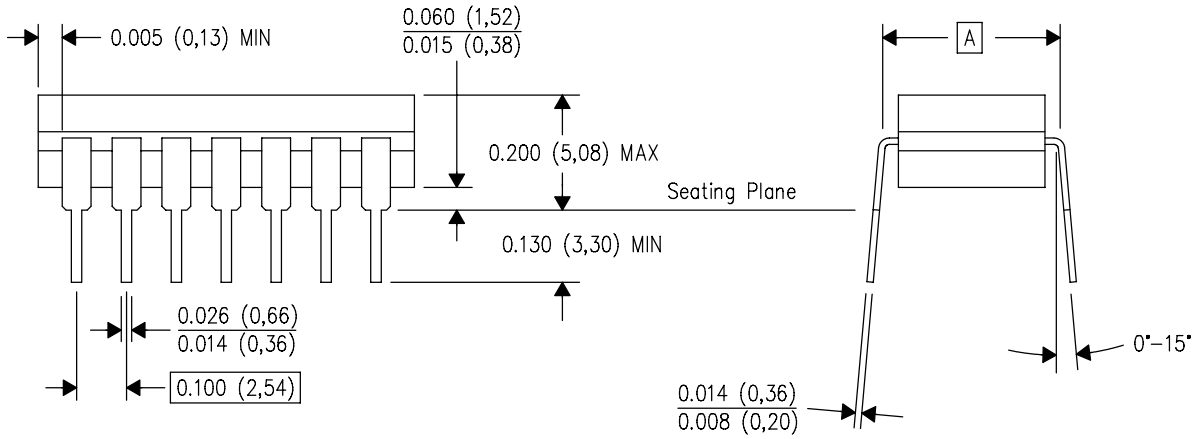
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

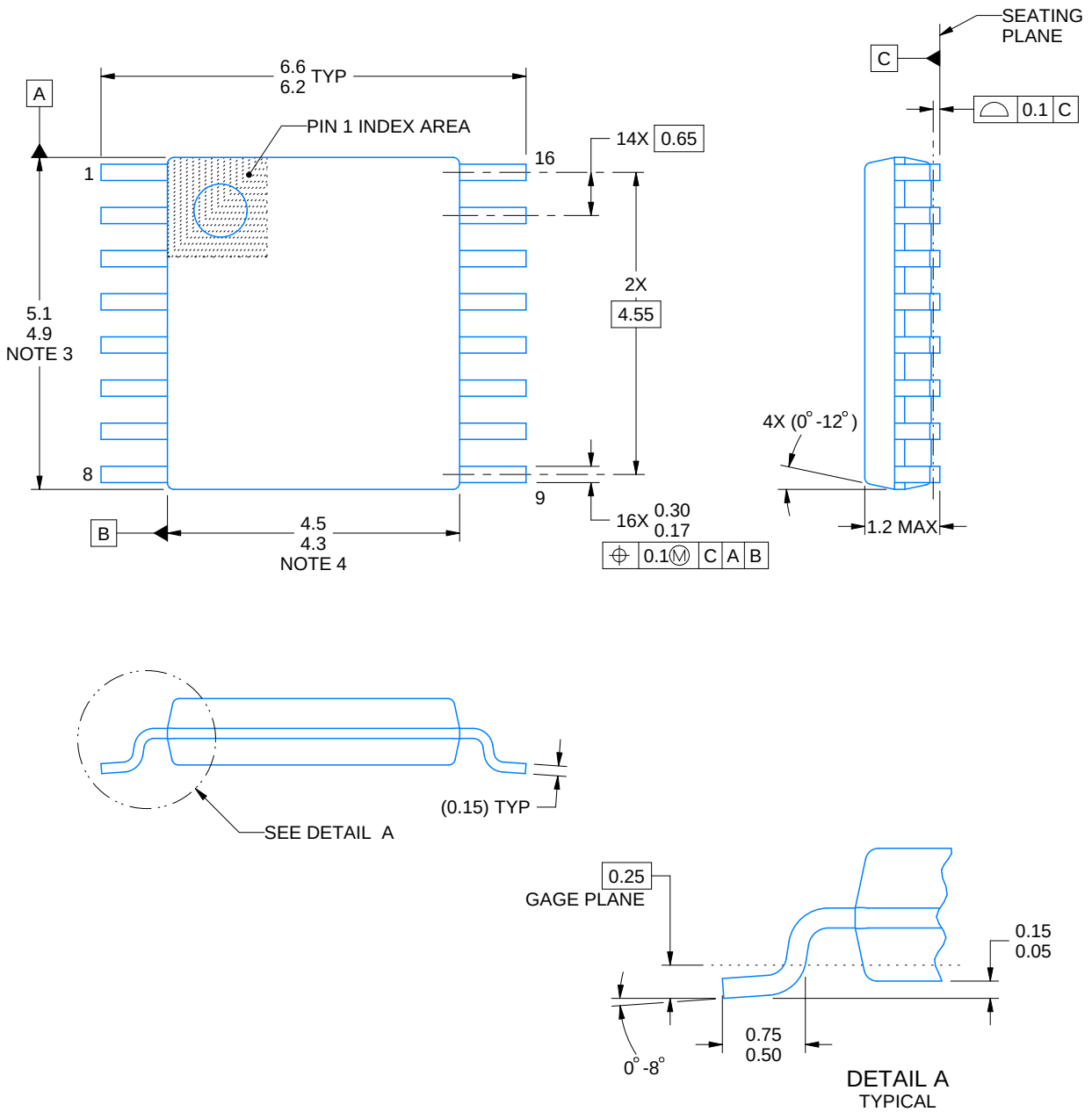
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

PACKAGE OUTLINE

PW0016A

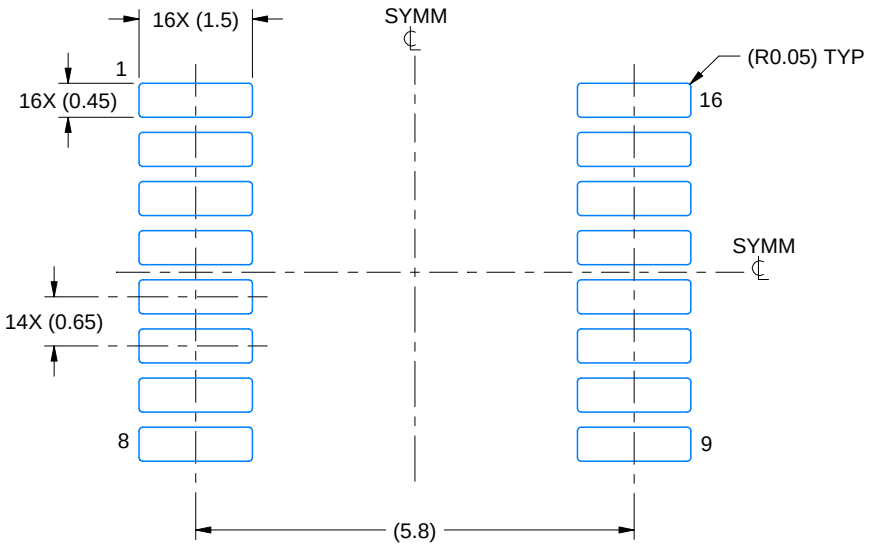
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.



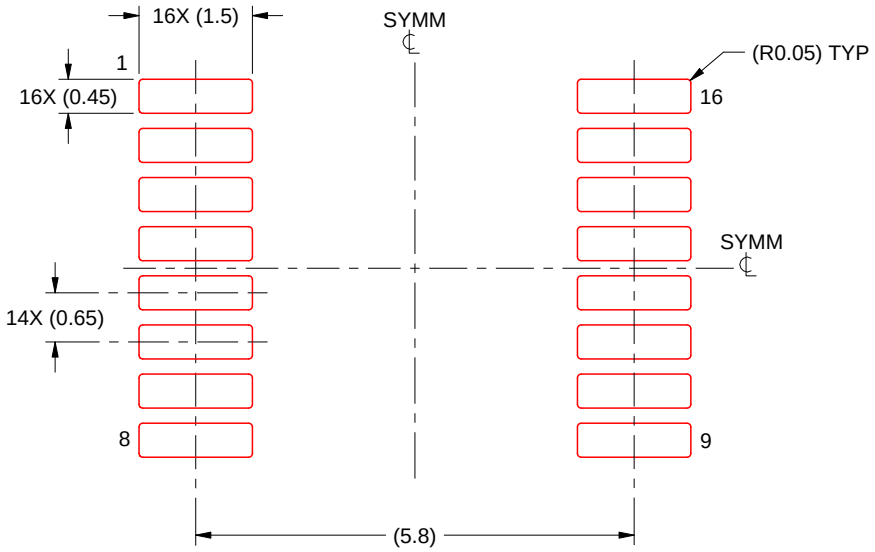
LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

SOLDER MASK DETAILS

4220204/B 12/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220204/B 12/2023

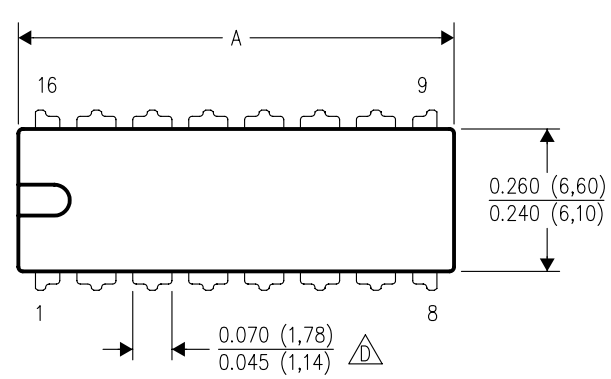
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

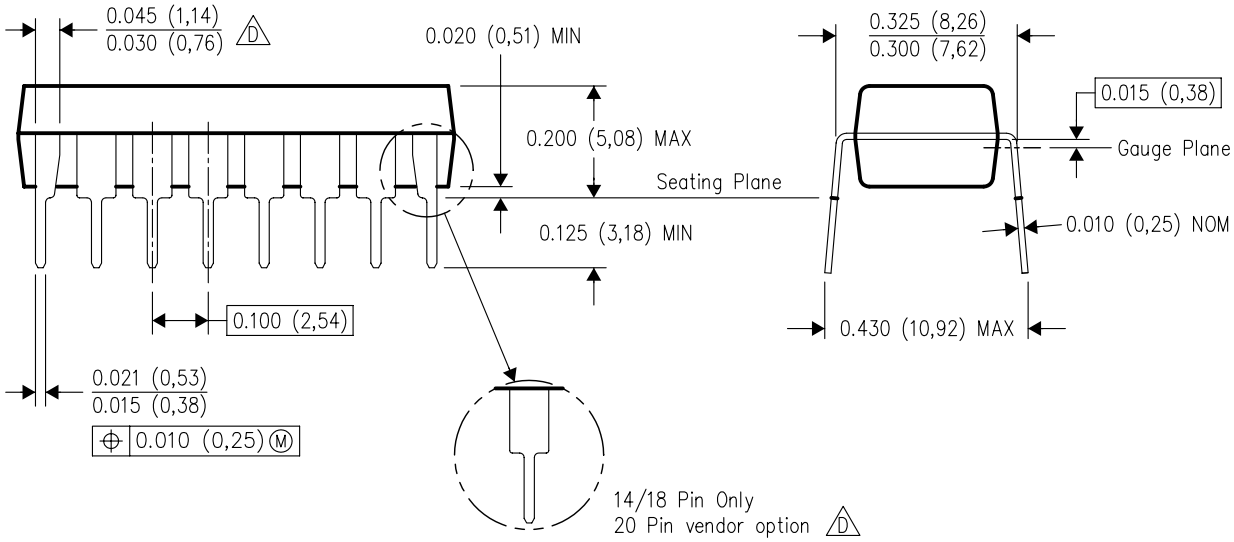
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

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